



CRYOGENIC CMOS FRONT-END FOR DARK MATTER DETECTION RESEARCH AND DEVELOPMENT



Student
Thesis advisor
Co-advisor

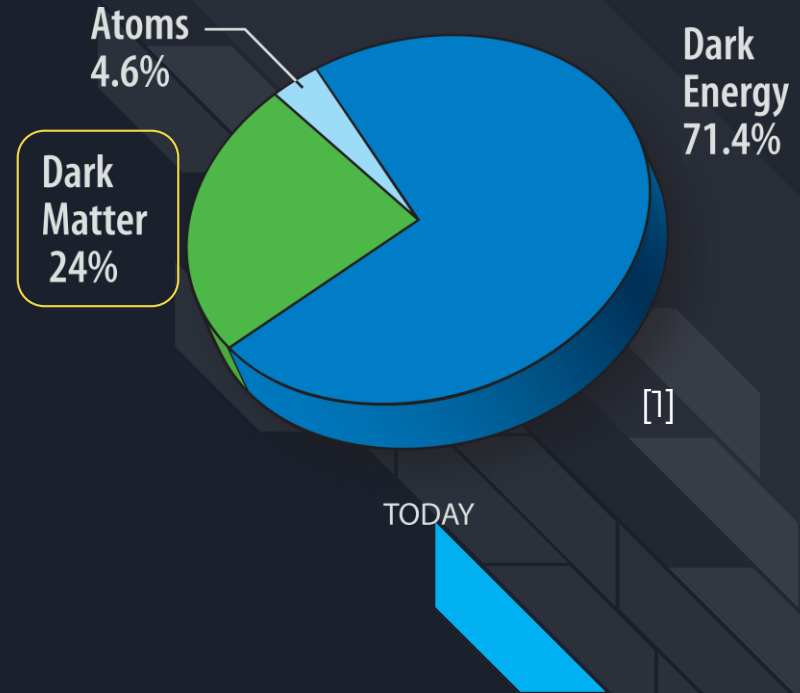
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What is Dark Matter?

Dark matter is believed to be composed by some form of a non-luminous* non-baryonic particles.

The only observable interaction with normal baryonic matter is through it's *gravitational* field.

*Non-Luminous \Rightarrow No interaction with e-m field



Dark Matter phenomenology

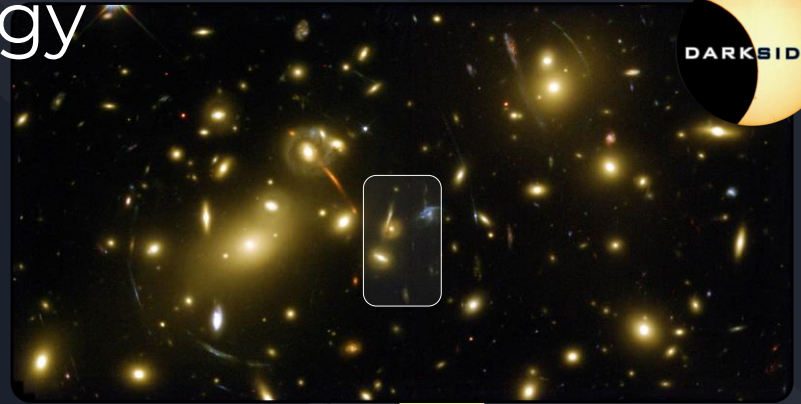
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Dark Matter phenomenology

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- Gravitational Lensing; [1]



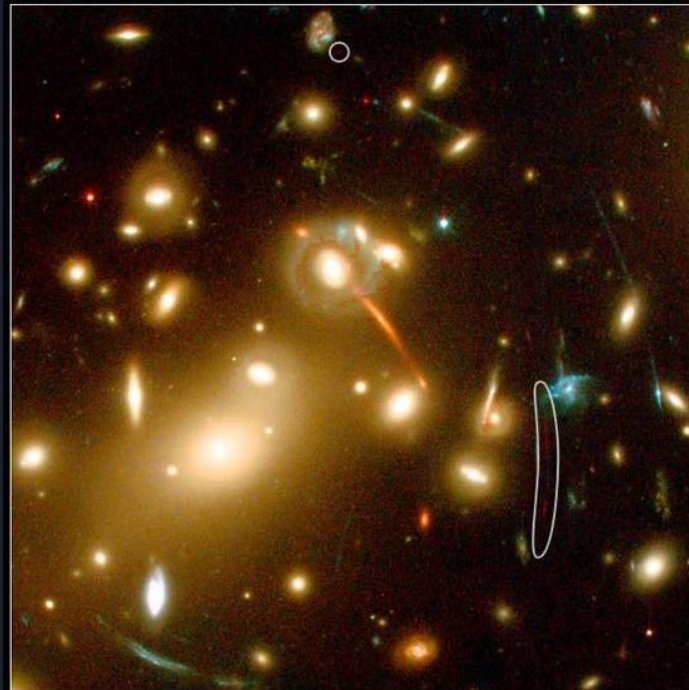
Dark Matter phenomenology

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- Gravitational Lensing; [1]



Distant Galaxy Lensed by Cluster Abell 2218 HST • WFPC2 • ACS



ESA, NASA, J.-P. Kneib (Caltech/Observatoire Midi-Pyrénées) and R. Ellis (Caltech) STScI-PRC04-08

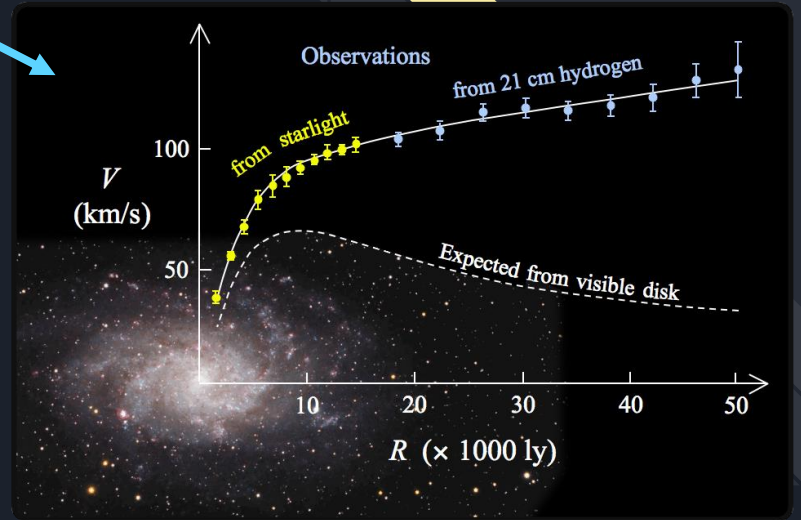
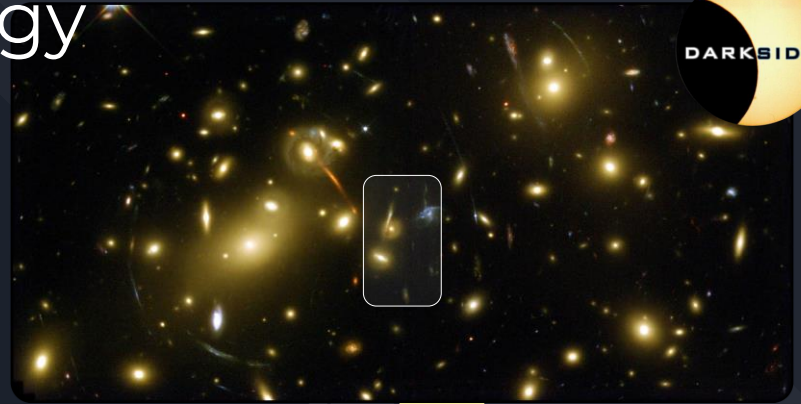


Dark Matter phenomenology



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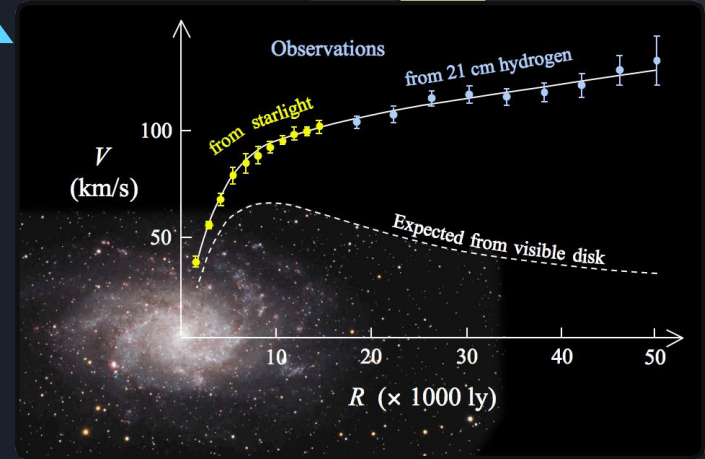
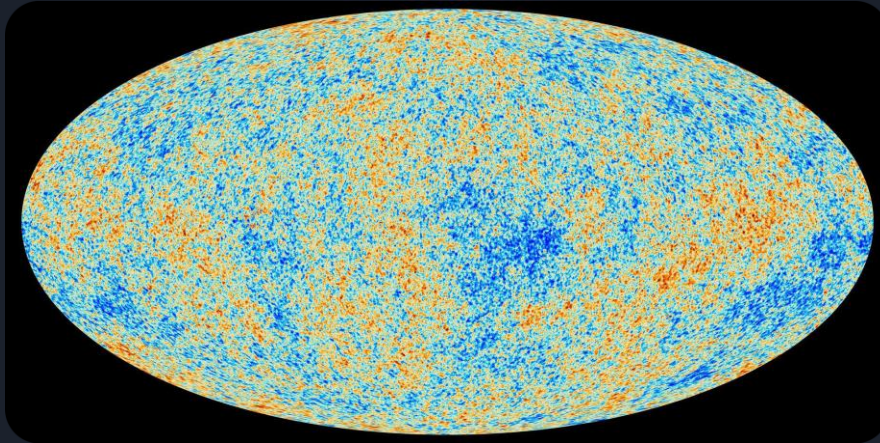
- Gravitational Lensing; [1]
- Galaxy Rotational Speed; [2]



Dark Matter phenomenology

There are many phenomena that are only explainable using DM, some of these are:

- Gravitational Lensing; [1]
- Galaxy Rotational Speed; [2]
- Cosmic Microwave Background anisotropies. [3]



How do we detect Dark Matter?



- *Direct* detection via shielded *underground* detectors;
- *Indirect* detection via *WIMP annihilation signals* captured by satellites, balloons or ground-based *telescopes*;
- *Direct* production of dark matter in high energy *particle accelerators*.

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What is DarkSide?^[4]

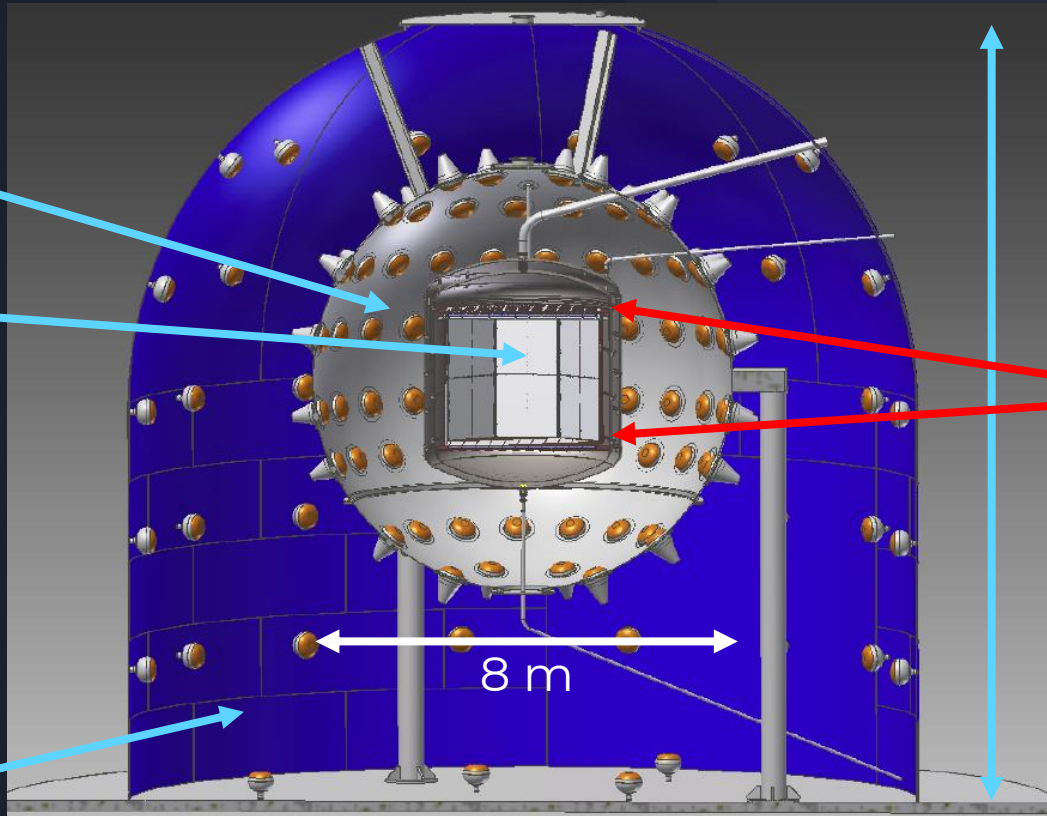


Height = 14.65 m

Liquid Boron scintillator tank used as an active neutron veto

20 ton liquid Argon TPC tank used for detecting DM, operating @ $T = 87\text{ K}$

Ultra-pure water tank used as an active muon veto



SiPM array

8 m

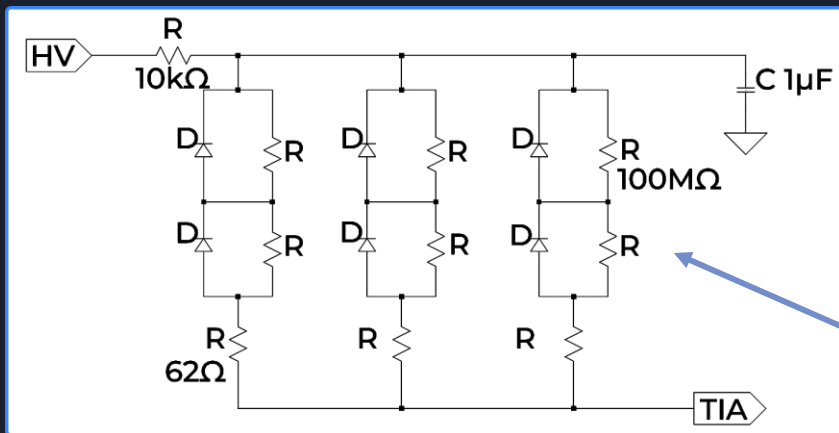
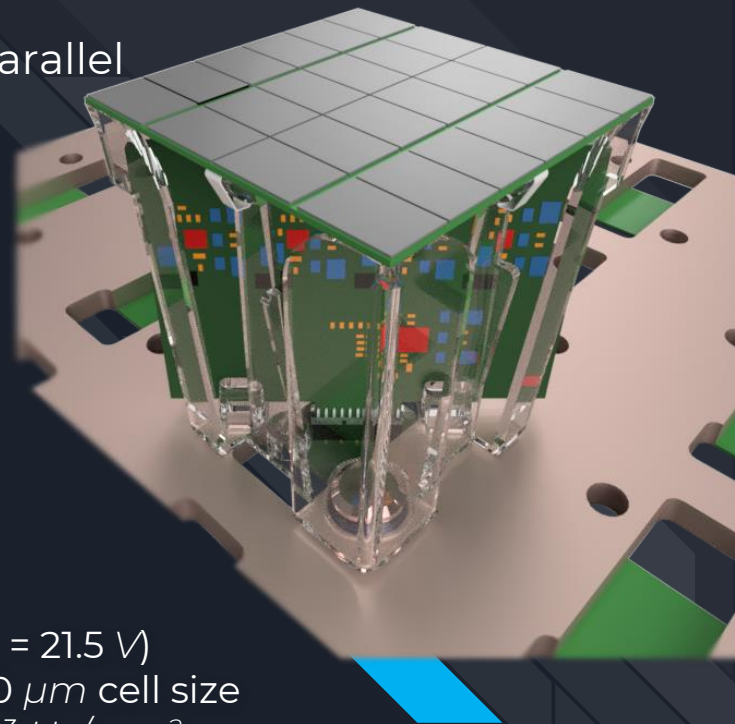
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Base diameter = 15 m

DarkSide PhotoDetector Module (PDM)^[5]

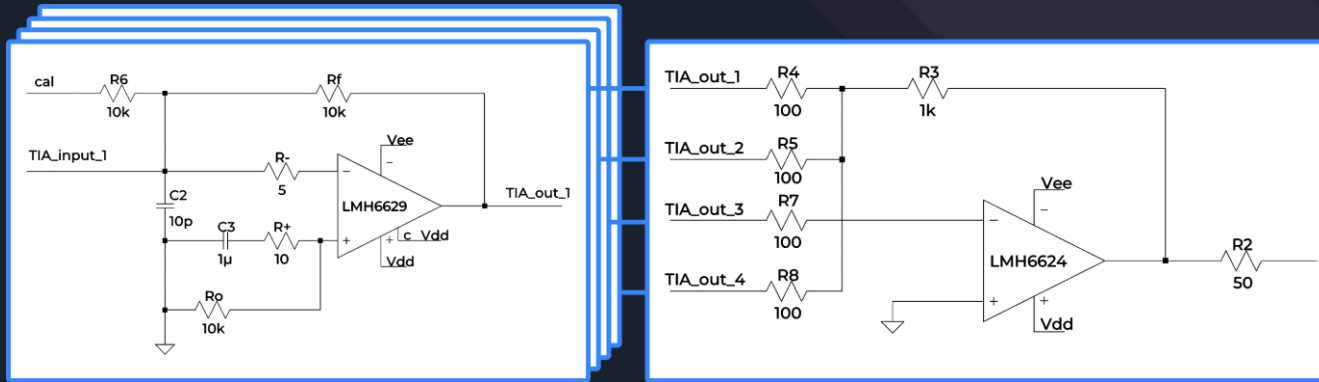


- Basic PDM: 24 independent sensors
- Each quadrant has 6 SiPMs: 2 in series and 3 in parallel
- Total sensing area: 24 cm^2
- SNR @ 77K for 1 PE: 10
- Time resolution: 20 ns
- Channel power consumption: 250 mW



$OV = 5 \text{ V}$ ($V_{BD} = 21.5 \text{ V}$)
SPAD with $30 \mu\text{m}$ cell size
 $DCR \approx 5 \times 10^{-3} \text{ Hz/mm}^2$

DarkSide current DISCRETE Front-End ^[5]



- 4 independent TIAs followed by a Summing Amplifier
- Bipolar SiGe operational amplifiers
- Single analog differential output per channel
- Power consumption: 250 mW

INTEGRATED vs DISCRETE Front-End



IC vs discrete PROS:

- Simplification of chip handling: 1 component vs 40 per channel
- Improved performance using an *ad-hoc design* of the core building blocks
- Less interconnection between parts with local signal processing and multiplexing
- Greatly diminished power consumption: 77 mW vs 250 mW

PROBLEM: IC technology isn't modelled outside military temperatures $-55 \div 125 \text{ }^{\circ}\text{C}$



Device characteristics are extrapolated by the simulator



Cryogenic operation could be different from simulations



Cryogenic CMOS: advantages and issues

ADVANTAGES

- Mobility increases
- Transconductance* increases
- Thermal noise decreases



Higher SNR

DISADVANTAGES

- Threshold voltage increases
- Hot electron effect increases (more energetic carriers)

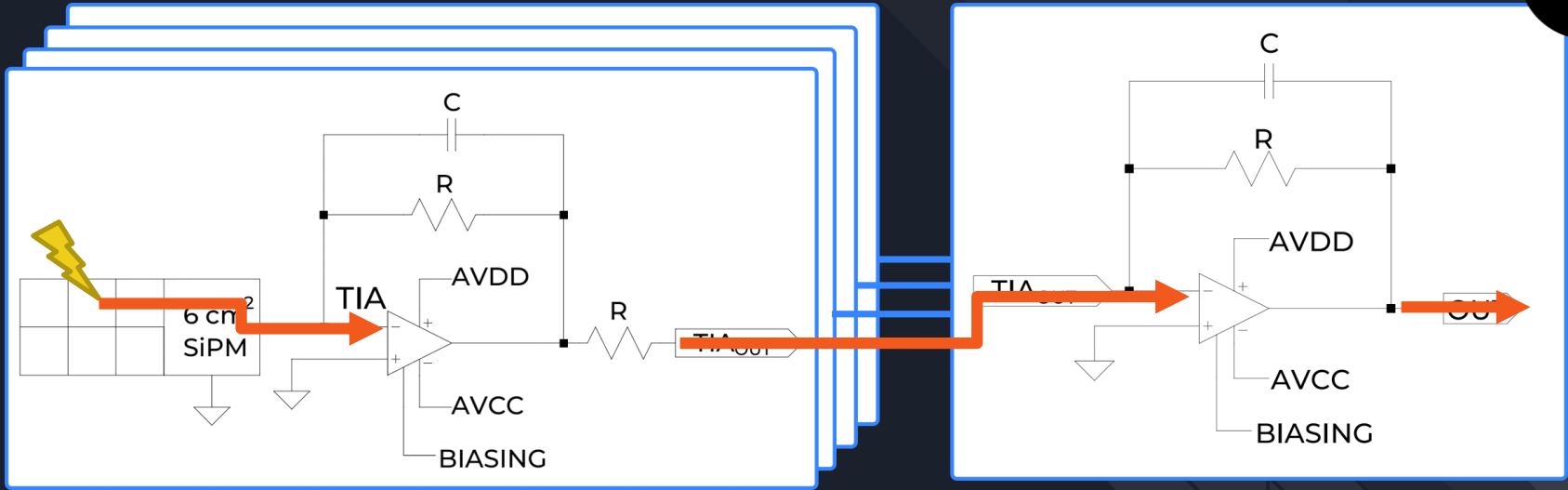


- Quicker Si-SiO₂ interface degradation
- Oxide trapped carriers ⇒ threshold voltage shift
- Worsened Gate leakage current (due to channel interface degradation)

$$* = g_m = \sqrt{2\mu C_{ox} \frac{W}{L} I_{DS}}$$



DarkSide CMOS Front-End: Top Level

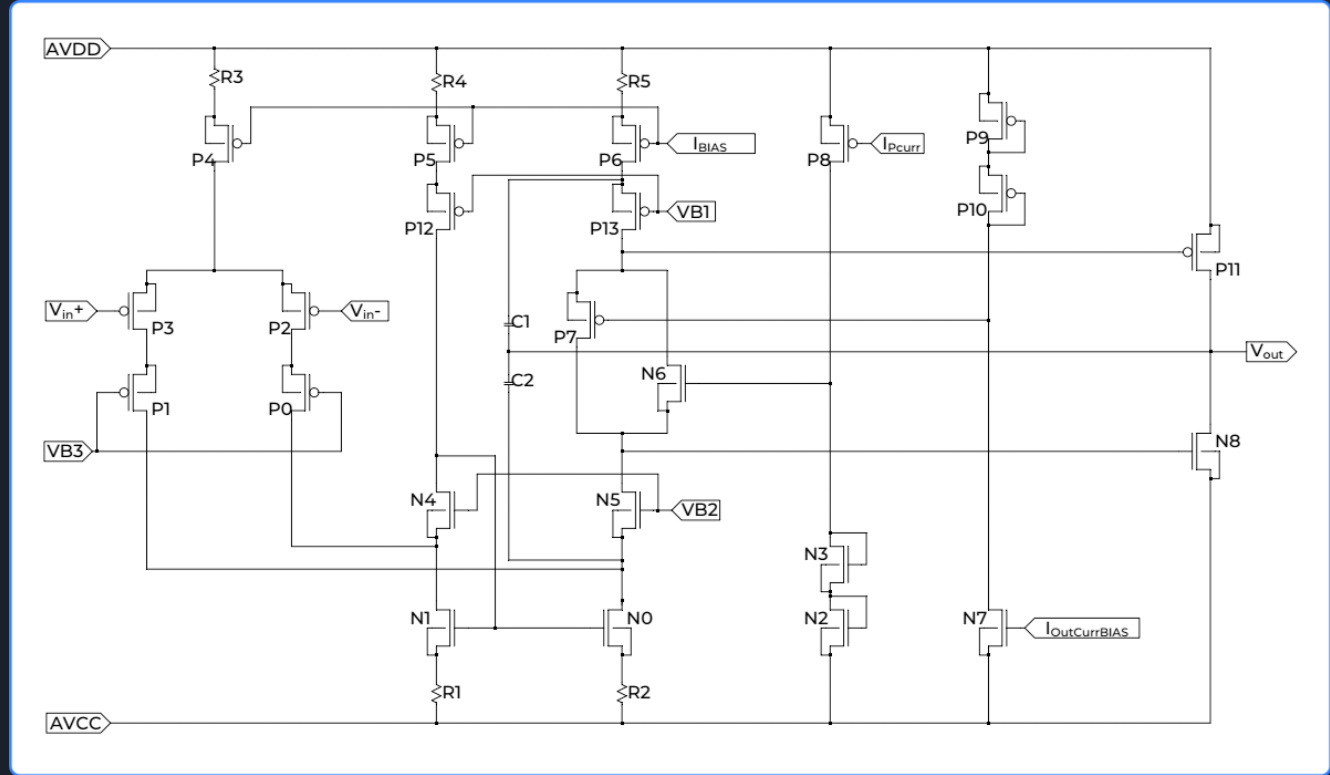


0. DM-LAr scattering generates a photon
1. SiPM detects this photon
2. TIA amplifies signal from SiPM
3. Amplified signal goes to summing amplifier
4. Summed signals are output to processing circuitry

DarkSide CMOS Front-End: Single Op-Amp



- Class-AB amplifier
- Low Bias currents
- High output range
- Gain scalability
- Dual Rail 2.5V supply





DarkSide CMOS Front-End: Single Op-Amp

- Thin oxide, wide area, *input* transistors for better transconductance and lower noise
- Voltage drop on input transistors reduced by using cascode transistors
- All other transistors designed with a thick oxide to enable 2.5V operation @77K and to generate lower noise

White Noise

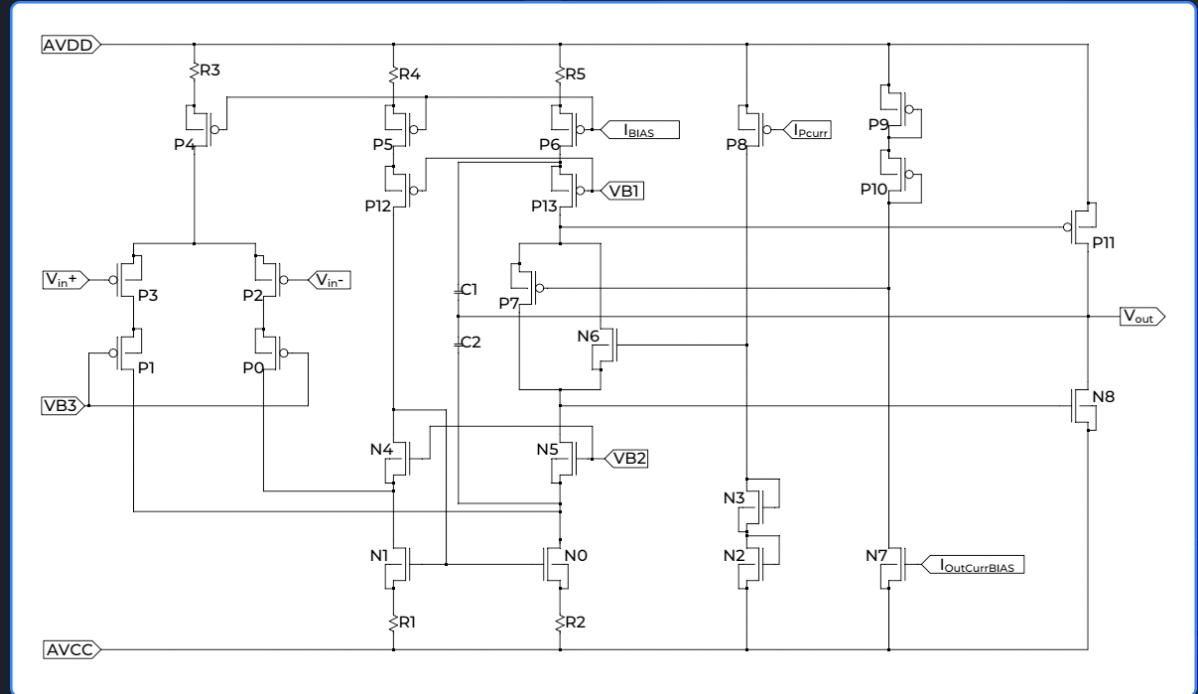
$$v_{n,w}^2 = 4k_B T \alpha_w \gamma \frac{1}{g_m}$$

Flicker Noise

$$v_{n,f}^2 = \frac{K_f(I_C, L)}{C_{ox}WL} \frac{1}{f^\alpha}$$

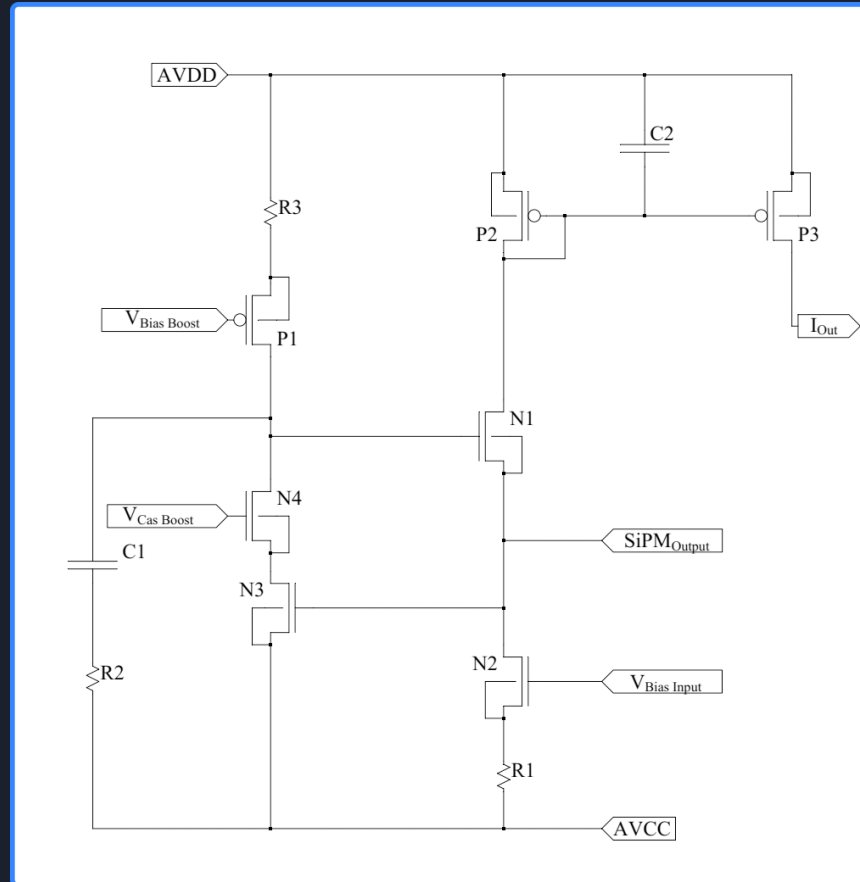
Noise on the x^{th} transistor

$$v_{n,x}^2 = 4k_B T \alpha_{w,x} \gamma_x \frac{g_{m,x}}{g_{m,in}^2}$$



CMOS Front-End: Regulated Common Gate

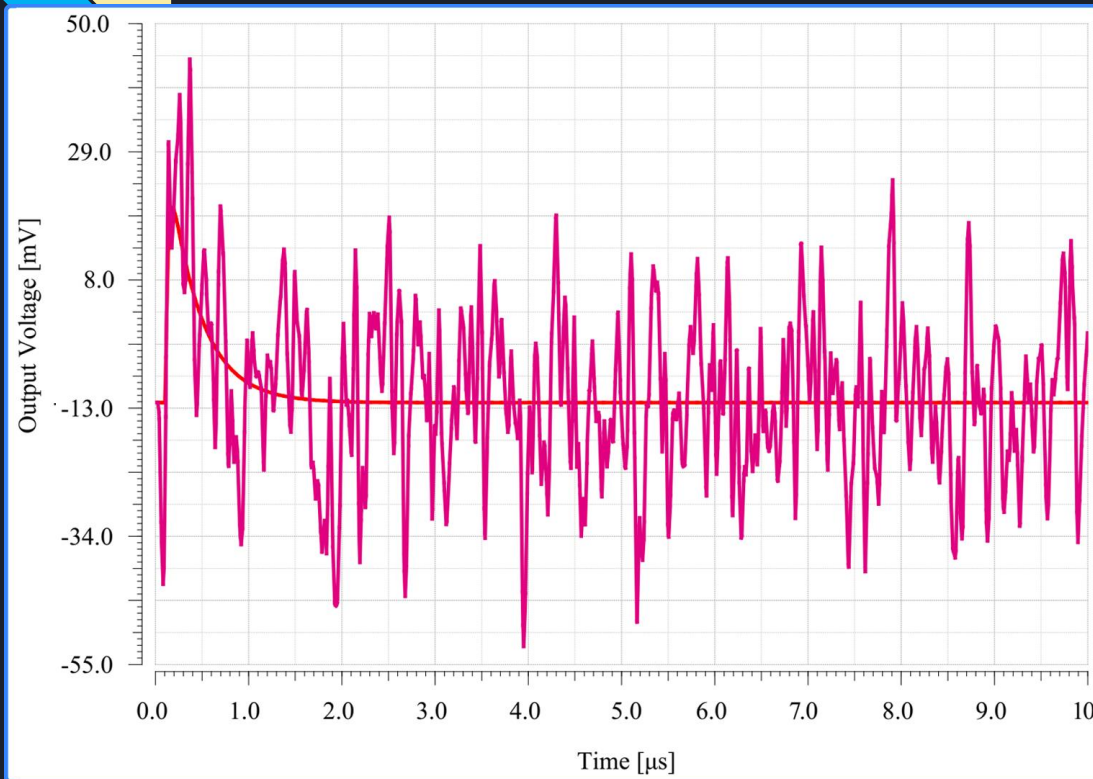
- N1 acts as a *common gate amplifier*
- N3 is used as a common source amplifier to reduce the input impedance
- P2 mirrors out the amplified current to P3
- P3 outputs the current to a shaper which transforms the current in a measurable voltage





▶ Output signal

▶ Superimposed noise



Characteristics

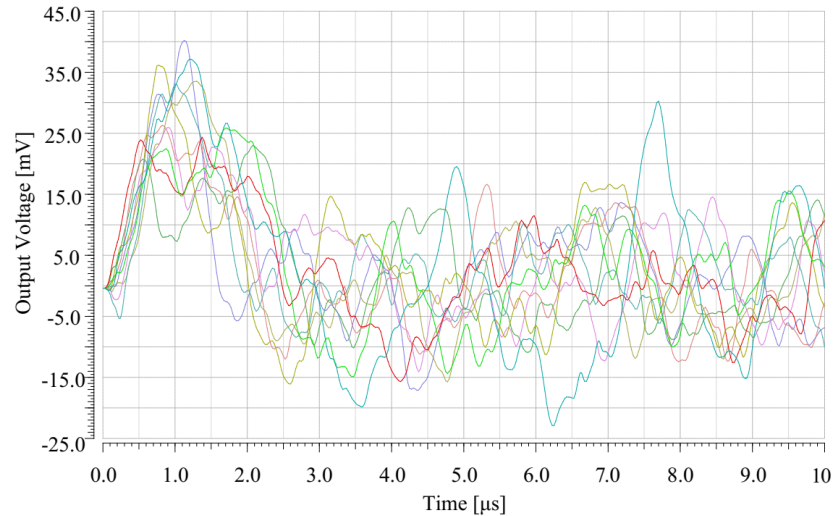
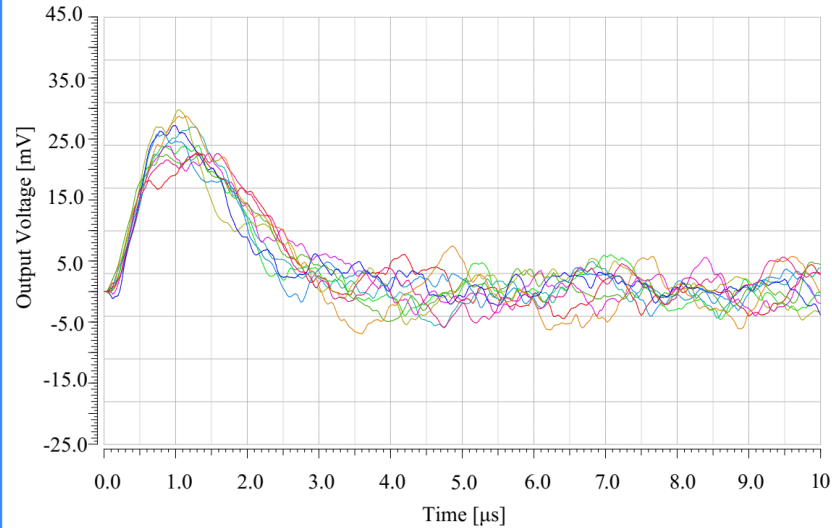
- $V_{pp} = 31.9 \text{ mV}$
- $V_{noise}^* = 16.1 \text{ mV}$
- $SNR^* \approx 2$
- $Jitter^* = 213 \text{ ns}$
- $F_{co} = 487 \text{ kHz}$
- $Power = 188 \text{ mW}$
- $Dynamic \text{ Range} = 50$

* *Caveat:* available SPICE files of LMH6629/4 do not model noise behavior at cryogenic temperatures.

OPAMP FE simulations

Temperature = 77K

Temperature = 300K



- $V_{pp} = 24.50 \text{ mV}$
- $V_{noise} = 2.67 \text{ mV}$
- $SNR = 9.19$
- $Jitter = 56 \text{ ns}$
- $Power = 79.96 \text{ mW}$
- $Dynamic Range = 45$

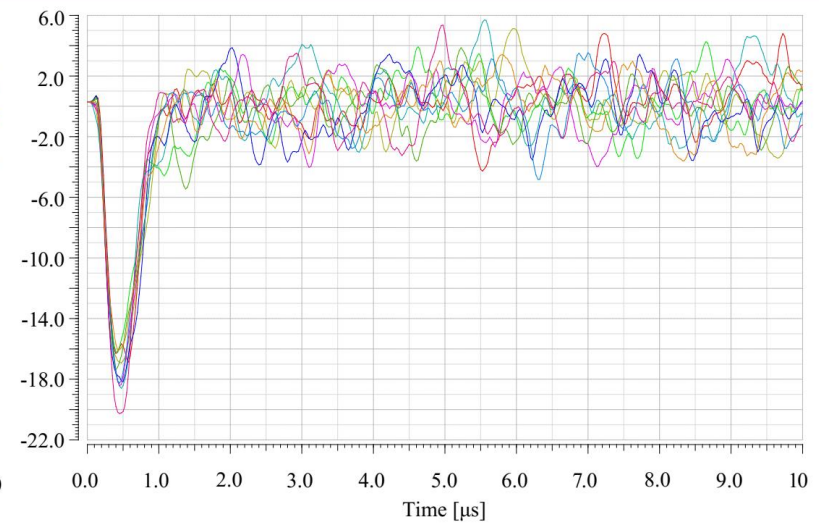
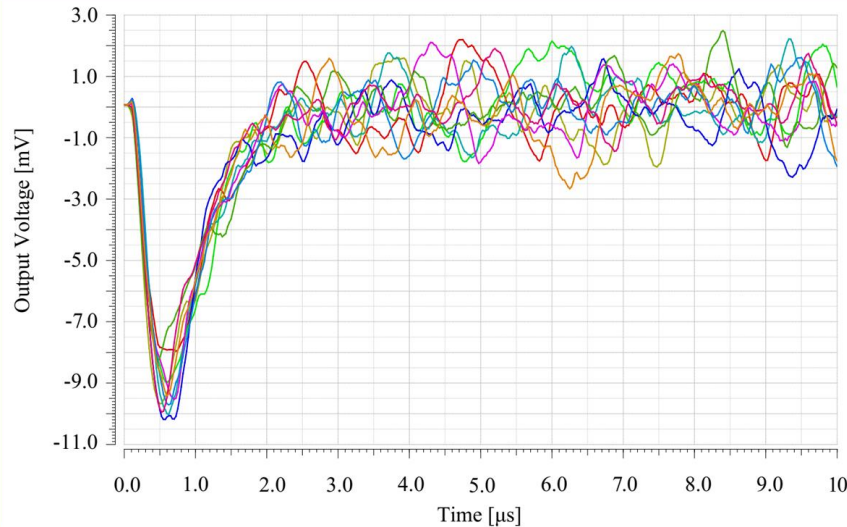
- $V_{pp} = 25.56 \text{ mV}$
- $V_{noise} = 8.16 \text{ mV}$
- $SNR = 3.13$
- $Jitter = 145 \text{ ns}$
- $Power = 71.47 \text{ mW}$
- $Dynamic Range = 35$

RCG FE simulations



Temperature = 77K

Temperature = 300K



- $V_{pp} = 11.54 \text{ mV}$
- $V_{noise} = 0.9 \text{ mV}$
- SNR = 12.78
- Jitter = 59.8 ns
- Power = 77.72 mW
- Dynamic Range = 105

- $V_{pp} = 18.2 \text{ mV}$
- $V_{noise} = 1.86 \text{ mV}$
- SNR = 9.78
- Jitter = 50.1 ns
- Power = 80.2 mW
- Dynamic Range = 30

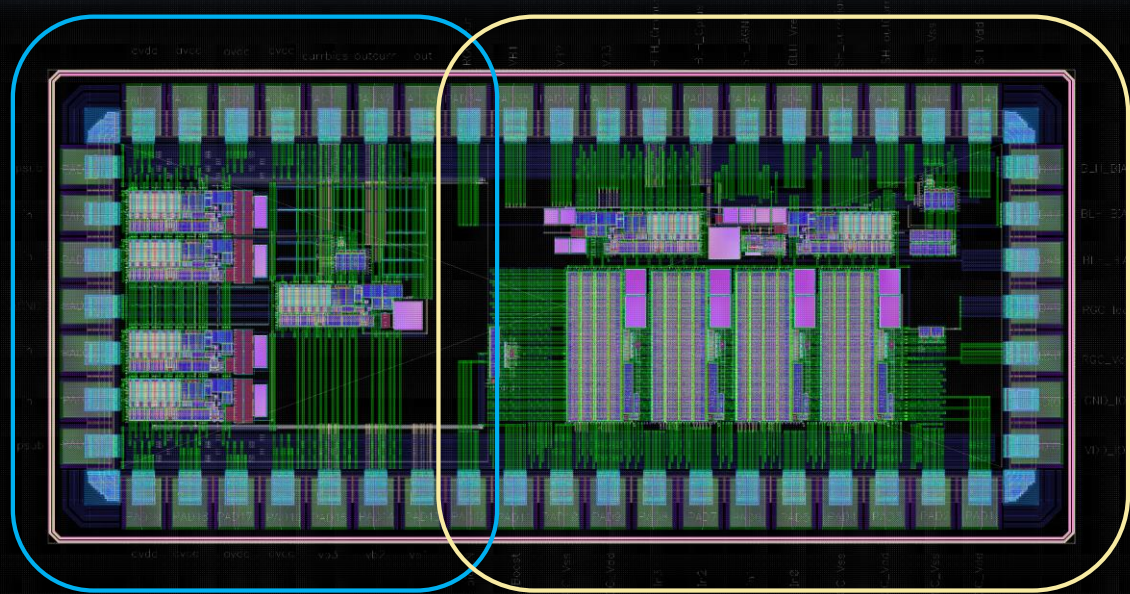


Model	DFE	OPAMP		RCG	
Temperature [K]	300	300	77	300	77
Peak to Peak Voltage [mV]	31.9	25.56	24.5	18.2	11.54
V_{noise}	16.09	8.16	2.67	1.86	0.9
SNR	1.99	3.13	9.19	9.78	12.78
Jitter [ns]	213	145.26	56.07	50.1	59.8
Power [mW]	188	71	80	80.2	77.72
DR	50	35	45	30	105

CMOS FE LAYOUT



- Submitted LAYOUT
- Technology UMC 110 nm
- ETA: end of April
- 1 mm x 2.5 mm
- **OPAMP**: 21 pads used
- **RCG**: 31 pads used



DS20K CMOS FE

To-Do List

- Characterize the physical front-end
- Biasing study
- Individual cryogenic circuit parts testing

DS20K CMOS FE

Thank you for your attention



Raffaele Aaron Giampaolo

References



1. [Nasa Wilkinson Microwave Anisotropy Probe](#)
2. [The Extended Rotation Curve and the Dark Matter Halo of M33](#)
3. [Cosmic Microwave Background Anisotropies](#)
4. [Development of electronics for a single-channel, 24 cm², SiPM-based, cryogenic photodetector](#)
5. [Cryogenic Lifetime Studies of 130 nm and 65 nm CMOS Technologies for High-Energy Physics Experiments](#)